



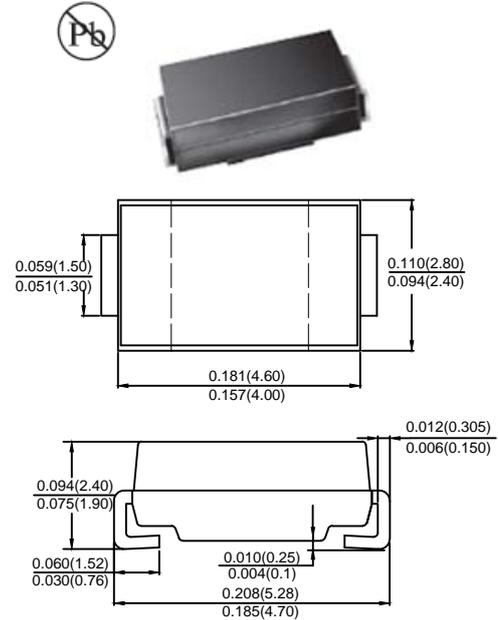
Features

- Low profile space
- Ideal for automated placement
- Glass passivated chip junctions
- Low forward voltage drop
- Low leakage current
- High forward surge capability
- High temperature soldering:
260°C/10 seconds at terminals
- Component in accordance to
RoHS 2002/95/1 and WEEE 2002/96/EC

Mechanical Date

- **Case:** JEDEC DO-214AC (SMA) molded plastic body over glass passivated chip
- **Terminals:** Solder plated, solderable per J-STD-002B and JESD22-B102D
- **Polarity:** Laser band denotes cathode end

SMA/DO-214AC



Dimensions in inches and (millimeters)

Maximum Ratings & Thermal Characteristics

Rating at 25°C ambient temperature unless otherwise specified
Single phase, half wave, 60Hz, resistive or inductive load
For capacitive load derate current by 20%

Type Number	SYMBOL	ES1A	ES1B	ES1D	ES1G	ES1J	Unit
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	V
Average Rectified Output Current @ $T_L=100^\circ\text{C}$	$I_{F(AV)}$	1.0					A
Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30					A
Rating for fusing ($t < 8.3\text{ms}$)	I^2t	5.08					A^2s
Forward Voltage @ $I_F=1.0\text{A}$	V_{FM}	1.0		1.25		1.65	V
Peak Reverse Current @ $T_A=25^\circ\text{C}$	I_R	5.0					μA
At Rated DC Blocking Voltage @ $T_A=125^\circ\text{C}$		200					
Maximum Reverse Recovery Time (Note1)	T_{rr}	35					ns
Typical Junction Capacitance (Note 2)	C_J	15					pF
Typical Thermal Resistance Junction to Ambient(Note 3)	$R_{\theta JA}$	110					$^\circ\text{C}/\text{W}$
Operating Temperature Range	T_J	-55 to +150					$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55 to +150					$^\circ\text{C}$

Note: 1. Reverse Recovery Test Conditions: $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $IRR=0.25\text{A}$.
2. Measured at 1.0 MHz and Applied reverse Voltage of 4.0V D.C
3. 8.0MM² (.013mm Thick) Land Areas.



Characteristic Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

Fig.1 Maximum Average Forward Current Rating

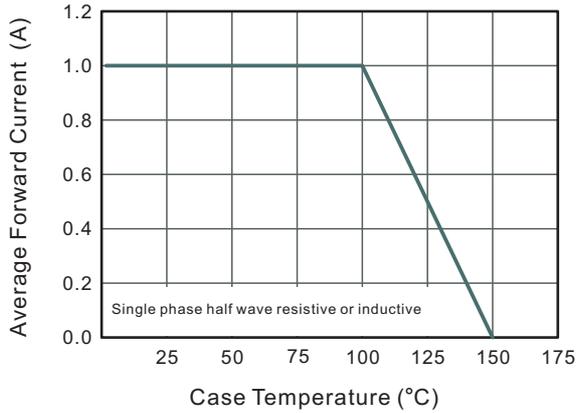


Fig.2 Typical Reverse Characteristics

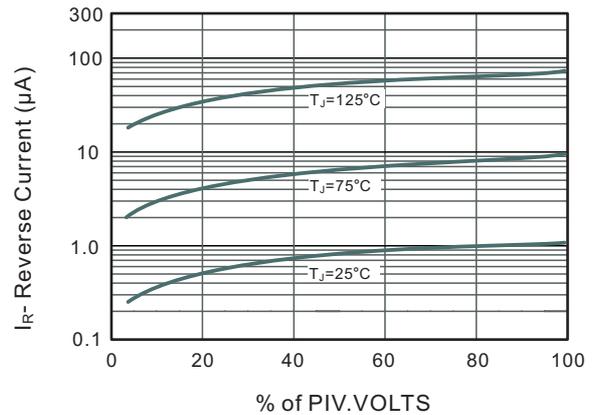


Fig.3 Typical Forward Characteristics

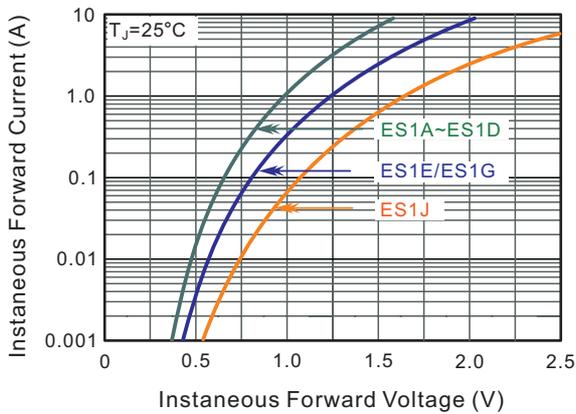


Fig.4 Typical Junction Capacitance

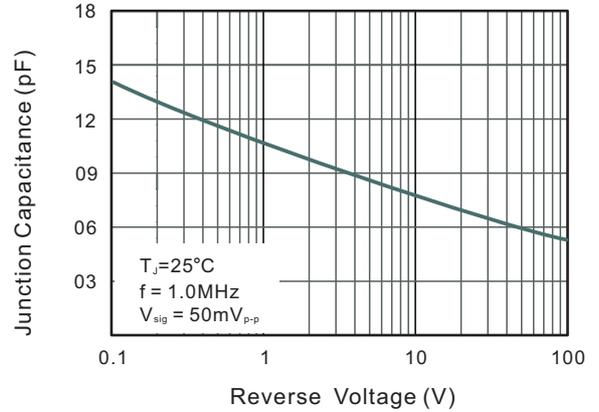
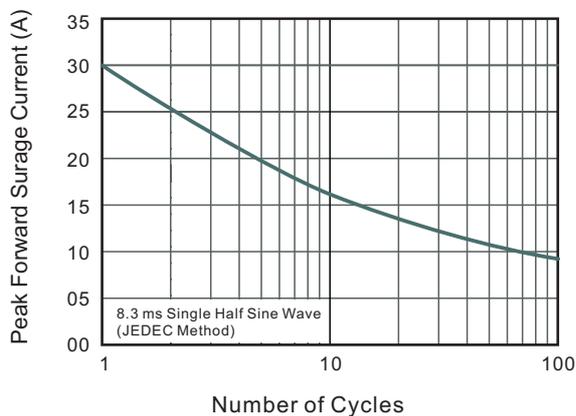


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



SMA PAD LAYOUT

